

A METHOD TO PREVENT CORROSION OF BOND PAD STRUCTURE

ABSTRACT

There is provided a method of fabrication an integrated circuit comprising providing a substrate with a bond pad formed thereover, the bond pad having a top surface for the formation of bonding connections. A passivation layer is provided over the bond pad followed by an overlying masking layer. The passivation layer is subsequently etched in accordance with the masking layer to form a patterned passivation layer with an opening that exposes a portion of the top surface of the bond pad. After etching the passivation layer, the mask layer is removed by a plasma resist strip followed by a wet solvent clean that removes etch residue from the passivation layer etch. Finally, a bond pad protective layer is grown over the surface of the bond pad. The bond pad may be composed of aluminum and the bond pad protective layer may be aluminum oxide.

Fig. 5